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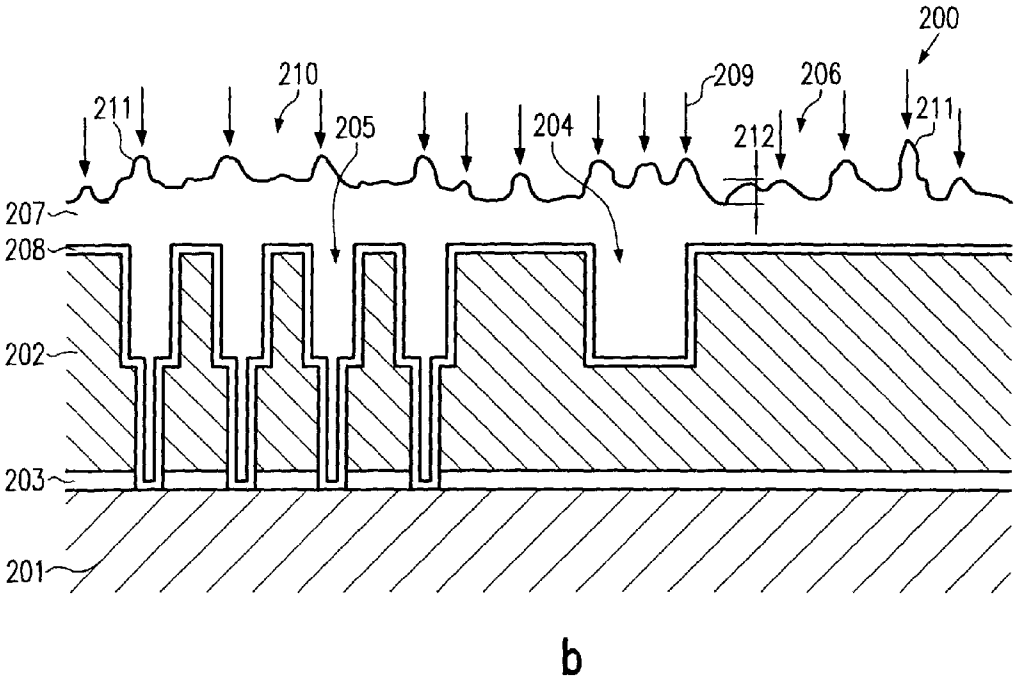
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(54) Title: METHOD OF ELECTROPLATING COPPER OVER A PATTERNED DIELECTRIC LAYER TO ENHANCE PROCESS UNIFORMITY OF A SUBSEQUENT CMP PROCESS



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(57) Abstract: In a new method of plating metal onto dielectric layers including small diameter vias and large diameter trenches (205), a surface roughness is created by e.g. reducing the amount of leveler in the plating bath at least on non-patterned regions (206) of the dielectric layer (203) to enhance the uniformity of material removal in a subsequent chemical mechanical polishing (CMP) process.

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